



Material Content Data Sheet



Sales Product Name				BSZ086P03NS3E G		Issued		29. August 2013	
MA#				MA000509266					
Package				PG-TSDSON-8-2		Weight*		38.76 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.835	4.73	4.73	47345	47345	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		54		
	non noble metal	zinc	7440-66-6	0.008	0.02		216		
	non noble metal	iron	7439-89-6	0.168	0.43		4326		
wire	non noble metal	copper	7440-50-8	6.808	17.57	18.03	175659	180255	
	non noble metal	copper	7440-50-8	0.034	0.09	0.09	875	875	
	encapsulation	organic material	carbon black	1333-86-4	0.034	0.09		869	
	plastics	epoxy resin	-	1.733	4.47		44729		
	inorganic material	silicondioxide	60676-86-0	15.063	38.87	43.43	388668	434266	
leadfinish	non noble metal	tin	7440-31-5	0.387	1.00	1.00	9990	9990	
plating	noble metal	silver	7440-22-4	0.963	2.48	2.48	24837	24837	
solder	non noble metal	tin	7440-31-5	0.037	0.10		950		
	noble metal	silver	7440-22-4	0.046	0.12		1187		
	non noble metal	lead	7439-92-1	1.758	4.54	4.76	45352	47489	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28		
	non noble metal	zinc	7440-66-6	0.004	0.01		111		
	non noble metal	iron	7439-89-6	0.086	0.22		2225		
	non noble metal	copper	7440-50-8	3.501	9.03	9.26	90341	92705	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49		
	non noble metal	zinc	7440-66-6	0.008	0.02		195		
	non noble metal	iron	7439-89-6	0.151	0.39		3894		
	non noble metal	copper	7440-50-8	6.127	15.81	16.22	158100	162238	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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